

Title (en)  
Wire saw device

Title (de)  
Drahtsäge-Vorrichtung

Title (fr)  
Dispositif de scie hélicoïdale

Publication  
**EP 2228186 A3 20110316 (DE)**

Application  
**EP 10156251 A 20100311**

Priority  
DE 102009012679 A 20090313

Abstract (en)  
[origin: EP2228186A2] The device has a cutting wire (140) guided over a wire guiding plate (110) and deflection rollers (120), and movable in a longitudinal direction using tensile strength. A sensor (135) is arranged in a periphery region (A) of the wire guiding plate or the deflection rollers. The sensor detects change of current position of a saw wire (140) with respect to a position given as an optimal position, which is transverse to a longitudinal axis of the saw wire. The sensor is formed as inductive-, magnetic- or optical sensor, and is formed as a proximity sensor with a pre-amplifier.

IPC 8 full level  
**B28D 1/10** (2006.01)

CPC (source: EP)  
**B28D 1/08** (2013.01); **B28D 1/10** (2013.01)

Citation (search report)

- [X] DE 10220640 A1 20021219 - WACKER SILTRONIC HALBLEITERMAT [DE]
- [X] US 5809986 A 19980922 - KATAMACHI SHOZO [JP]
- [X] EP 1738886 A1 20070103 - HCT SHAPING SYSTEMS S A [CH]
- [XD] DE 10003240 B4 20080821 - SUPER SILICON CRYSTAL RES INST [JP]
- [A] JP H0349863 A 19910304 - SUMITOMO METAL IND, et al
- [A] JP H0871911 A 19960319 - TOKYO SEIMITSU CO LTD
- [A] JP H0724724 A 19950127 - NIPPEI TOYAMA CORP

Cited by  
DE102016220523B4; CN115870571A; DE102016220523A1; CN108407116A; US2016303669A1; US9902000B2

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

Designated extension state (EPC)  
AL BA ME RS

DOCDB simple family (publication)  
**EP 2228186 A2 20100915; EP 2228186 A3 20110316; DE 102009012679 A1 20100916**

DOCDB simple family (application)  
**EP 10156251 A 20100311; DE 102009012679 A 20090313**